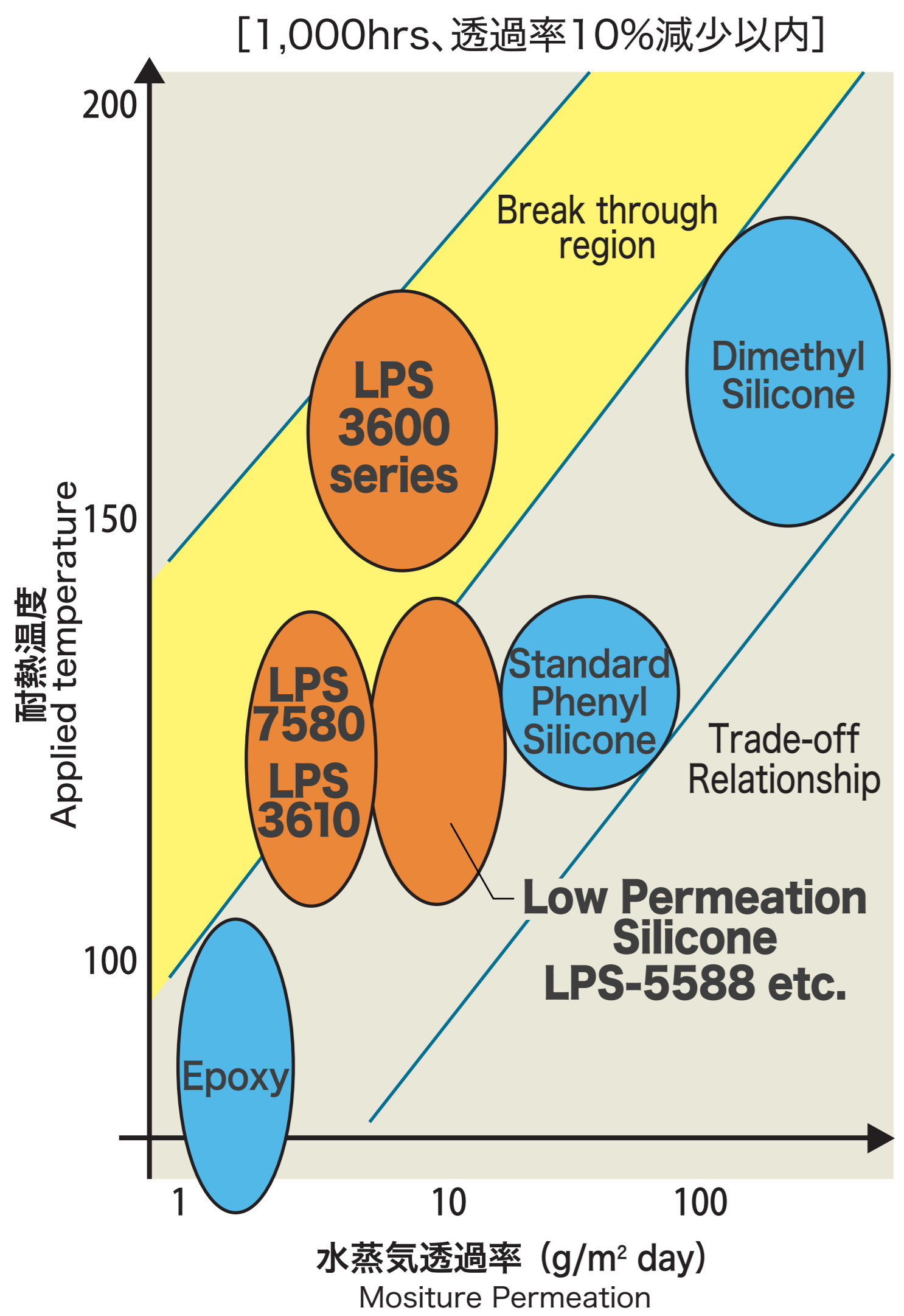
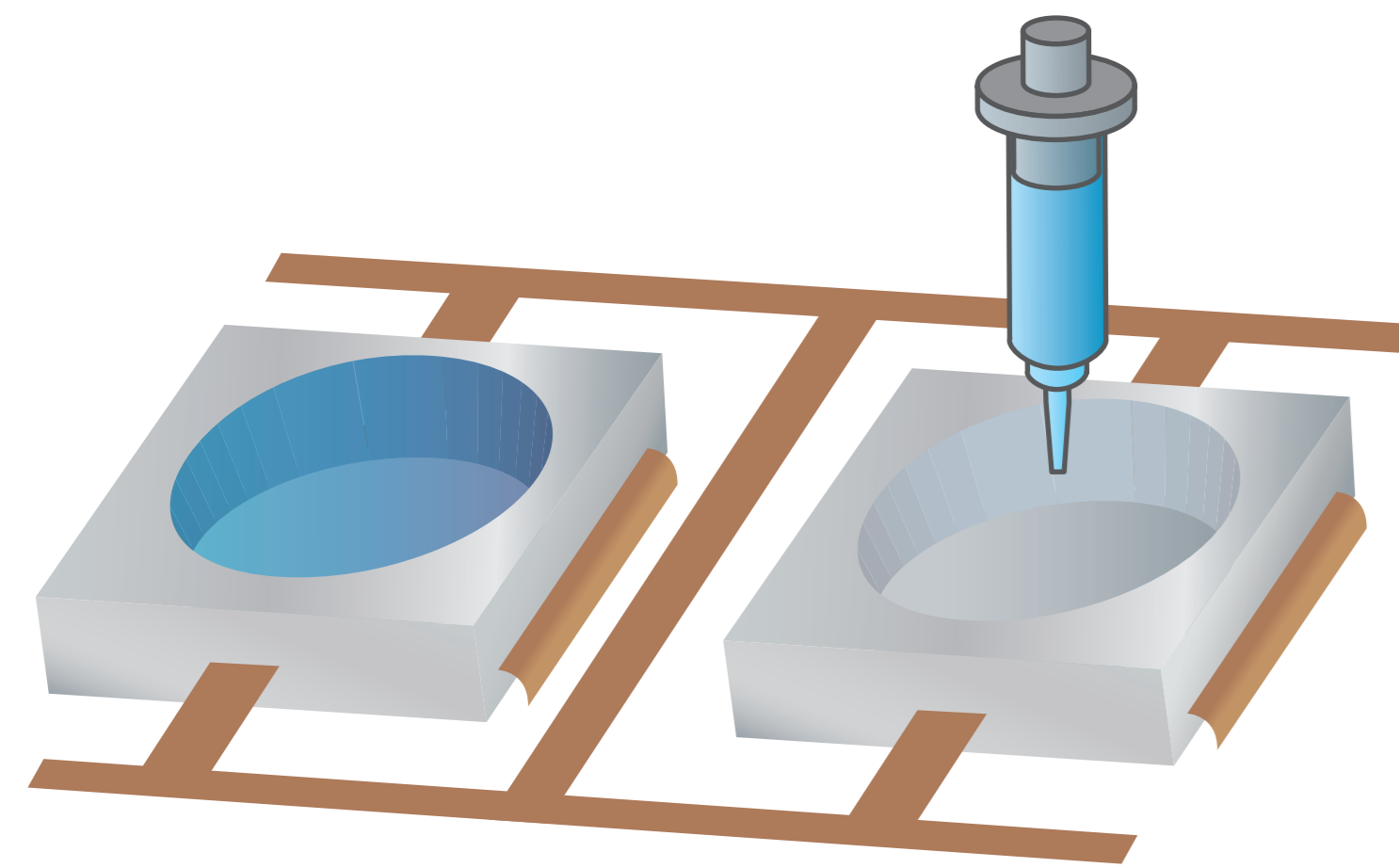


LED用材料 LimpidSi® series

Silicone materials for LED

ポッティング材(封止材)

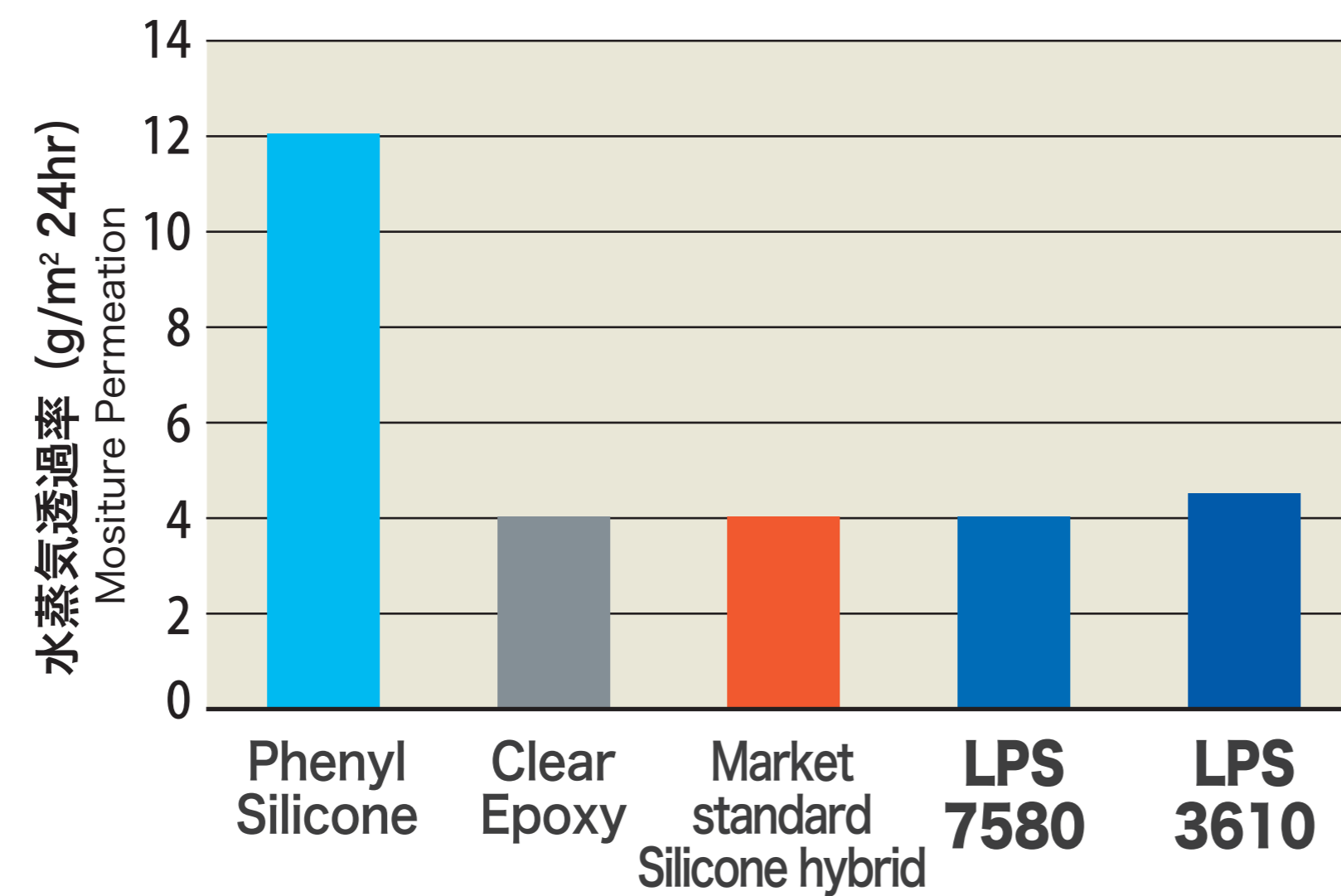
Potting materials (Encapsulant)



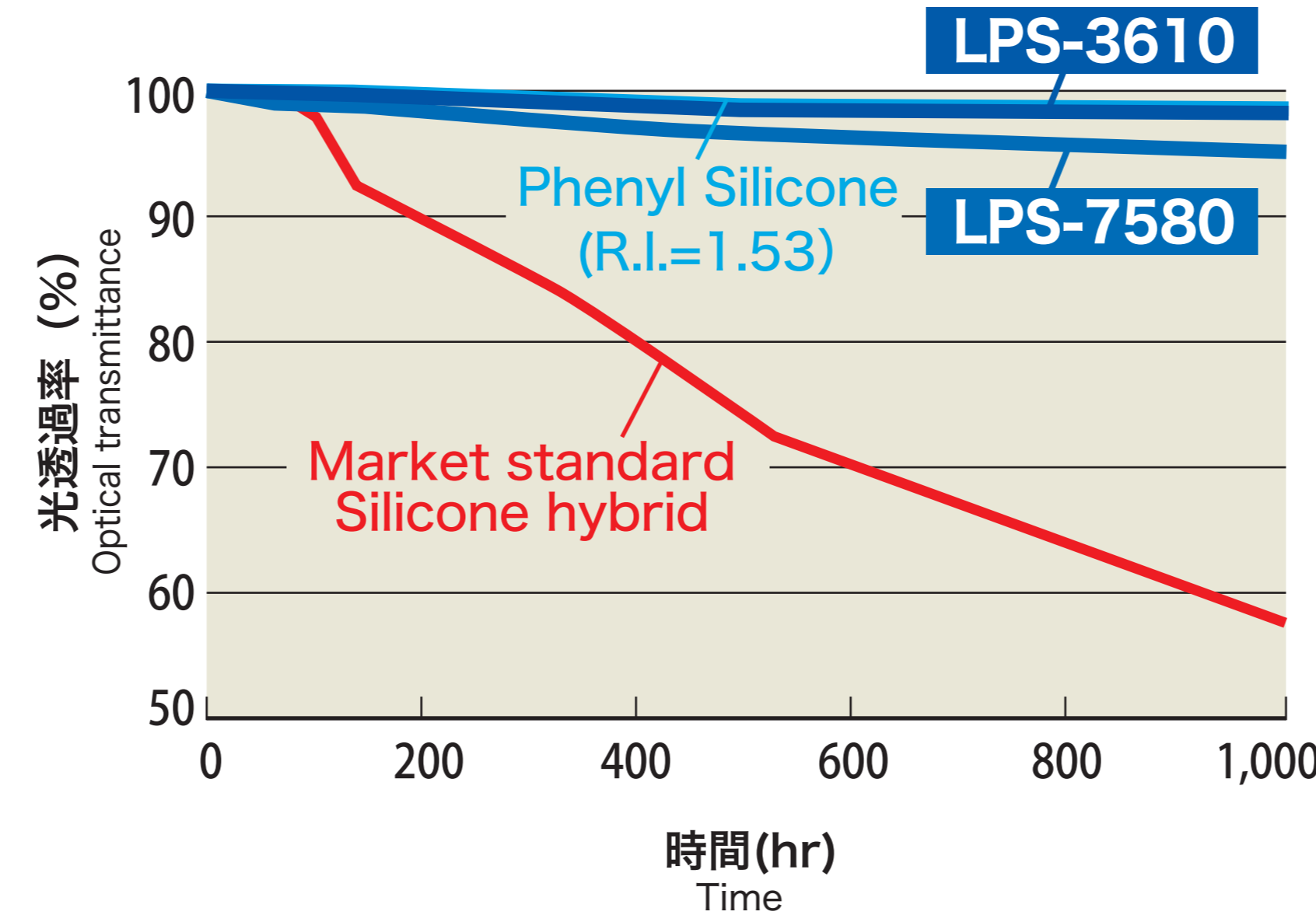
耐硫化、高屈折率封止材:LPS-7580 (R.I.=1.54), LPS-3610 (R.I.=1.57)

Encapsulant with sulfur resistance, high refractive index

低透湿: 4~6 g/m² day
Lower moisture permeance



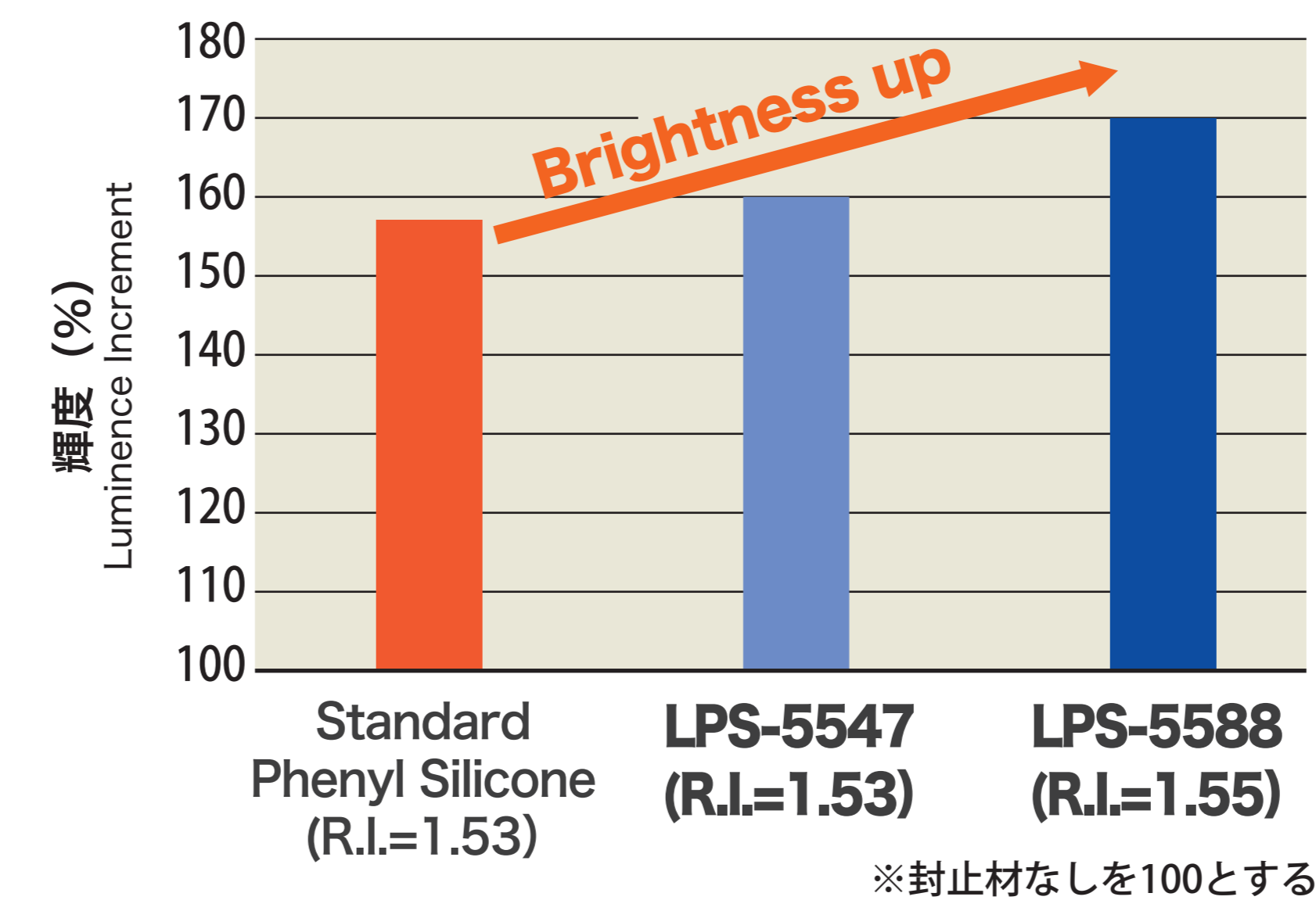
耐熱性: 150°C
Thermal resistance



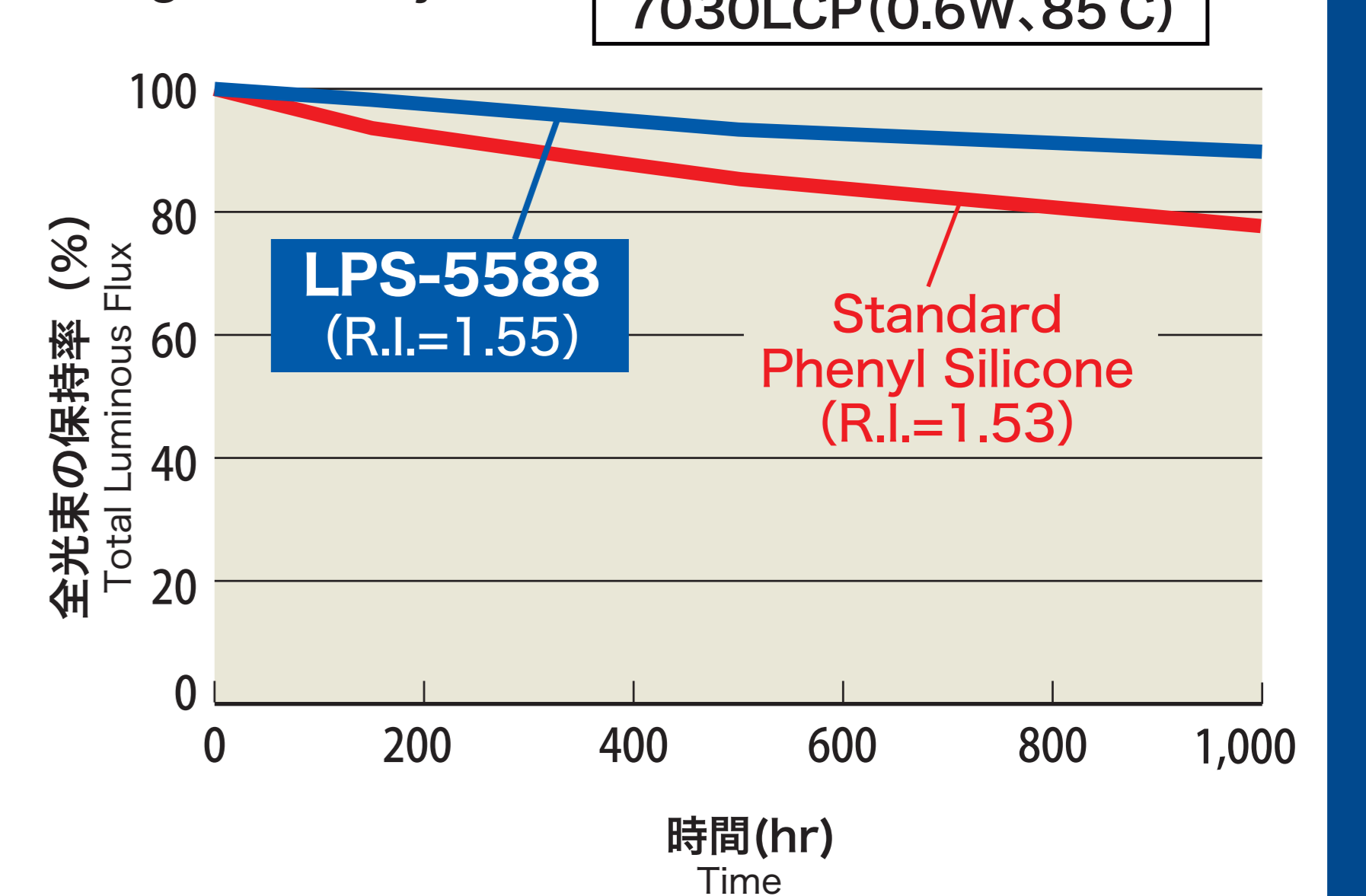
高輝度LED用封止材:LPS-5588

Encapsulant for high luminosity LED

高輝度
High luminosity



高信頼性
High reliability



EMC-PKG用封止材:LPS-5547SL-1

Encapsulant for EMC-PKG

		LPS-5547SL-1
粘度 Viscosity	Pa·s	7
密度 Density	g/cm³	1.16
硬度 Hardness	TypeA	85
引張強度 Tensile strength	Mpa	4
切断時伸び率 Elongation	%	100

リフローテスト: EMC-PKG
Reflow test

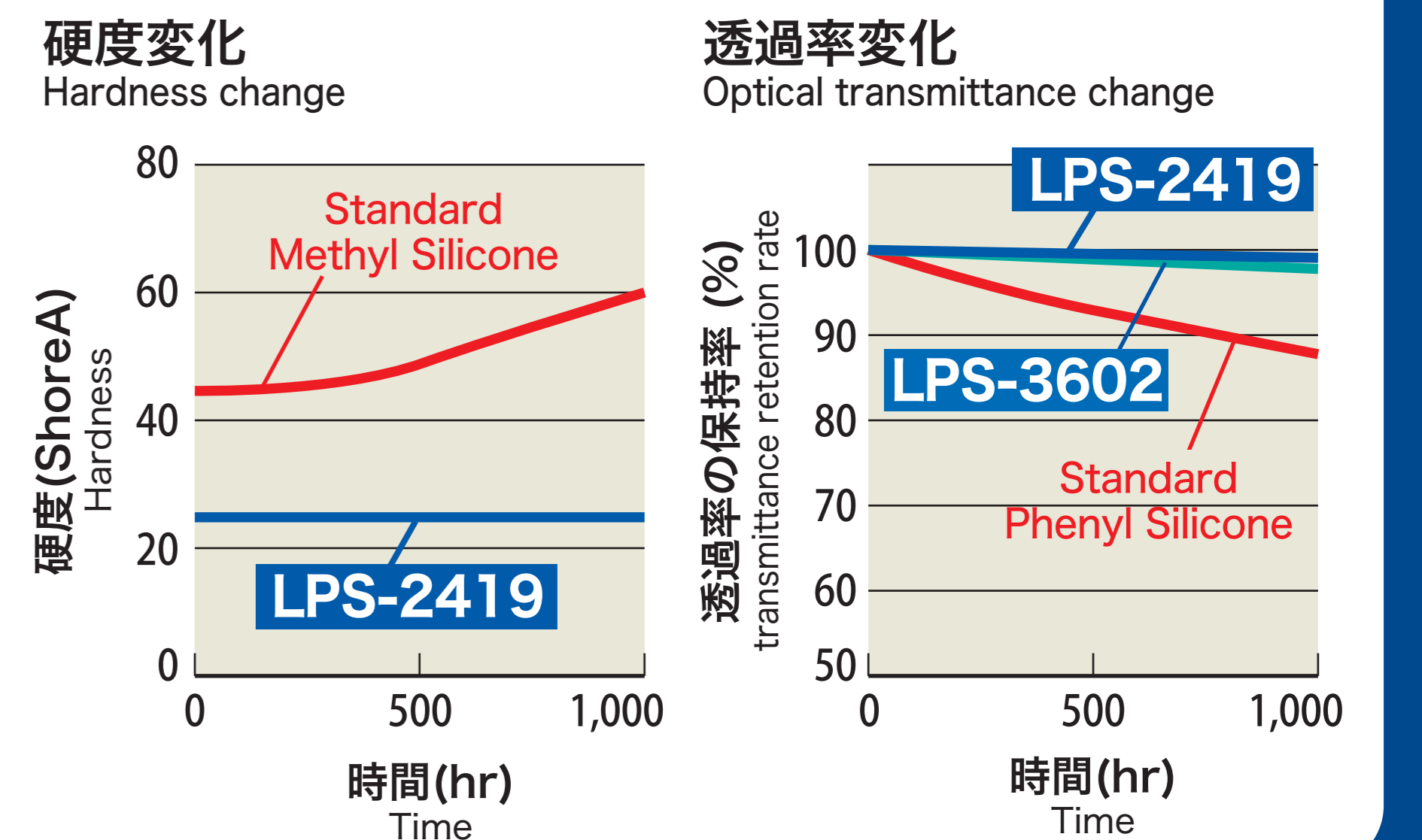
		LPS-5547SL-1
クラック Crack		0/10
剥離 Delamination		0/10

高耐熱封止材:LPS-3600 series, LPS-2419

Encapsulant with high thermal resistance

	LPS-3602	LPS-3602LL	LPS-2419
用途 Application	—	金型成形	ポッティング
屈折率 Refractive index	—	1.55	1.41
粘度 Viscosity	Pa·s	18.0	6.0
硬度 Hardness	ShoreA	70	27
伸び Elongation	%	40	105
透湿率 Moisture permeability	g/m²day	10	>100

高耐熱性 (180°C)
High thermal resistance



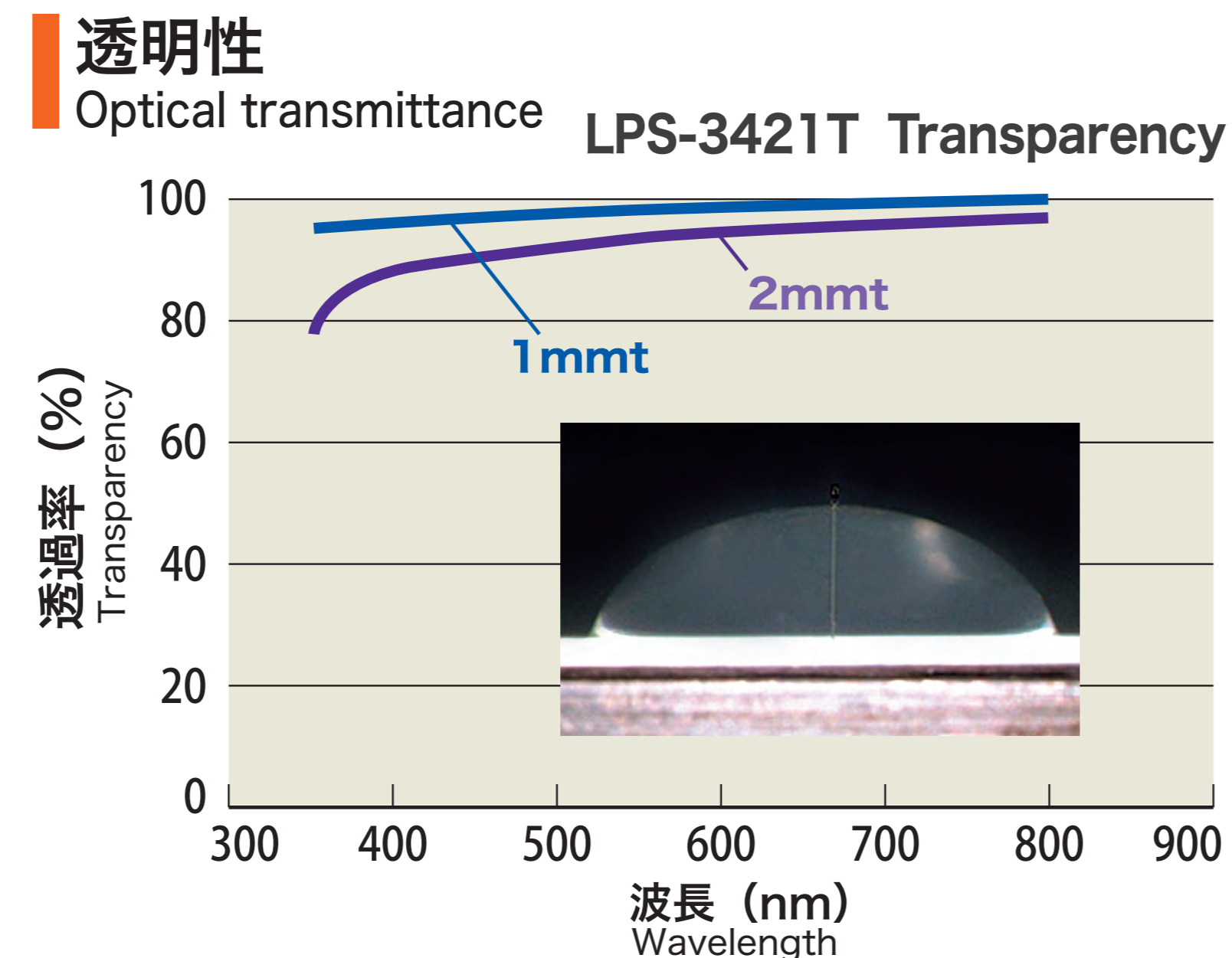
シリコンダイアタッチ材

Silicone die attach materials

	LPS-8445S	LPS-8445WTF-4	KJR-632DA-7L	
熱伝導率 Thermal conductive	W/mk	0.2	0.7 白色	7.0 電気伝導
光反射率 :450nm Optical reflection	%	—	>98	55
低揮発性 Low volatile	—	0.1	0.3	0.6

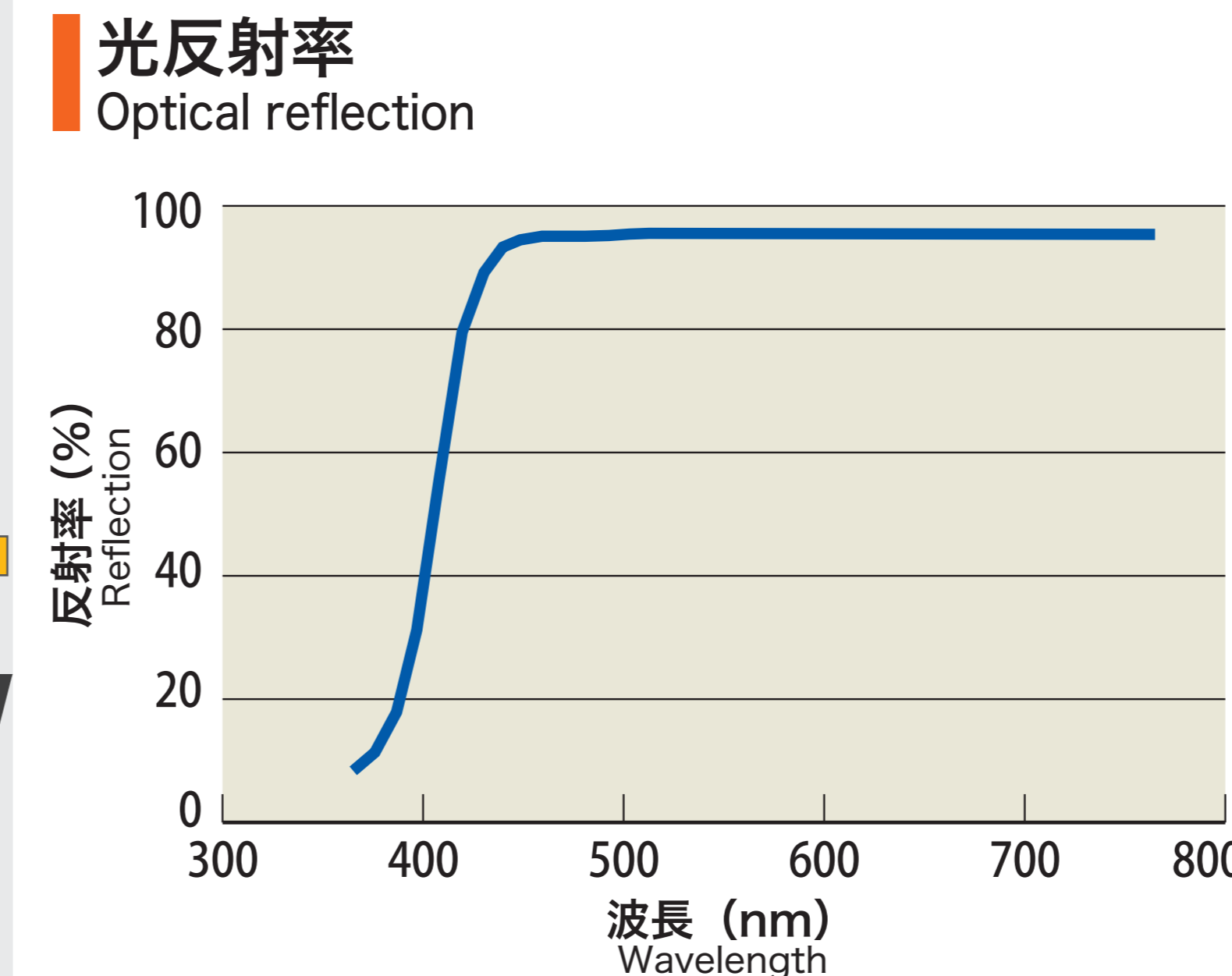
レンズ材:LPS-3421T

Dispensable lens form



ダム材:LPS-2428TW

Dam materials



金型成形材料(封止材)

Molding materials (Encapsulant)

圧縮成形材料
Compression Mold

トランスファー成形材料
Transfer Mold

	Dimethyl LPS-5400	Phenyl LPS-5588	Phenyl LPS-3541	Phenyl LPS-3602
屈折率 Refractive index	1.41	1.55	1.50	1.55
硬度 Hardness	D=30	D=40	A=70	A=70